



# Wafer-Level Optic Solutions

#### **Applications**

- Micro-optics and substrates
- Refractive and diffractive optical elements (ROEs & DOEs)
- 3D sensors, optics, spacers, heat sinks, and camera optics
- Beam shaping elements
- Homogenizers and optical sensors
- RF components
- Nanoimprint lithography substrates
- Hard disk masters and molds
- Blazed-wavelength and sub-wavelength diffraction gratings

## Benefits of Corning Wafer-Level Optic Solutions

- Various melting and forming methods enable significant volume supply of high-precision wafers with lowest thickness variation: part to part and batch to batch
- Compatible with wafer-level optic and semicon manufacturing processes and legacy equipment and tools
- Supporting capabilities include ceramics, automated laser glass-cutting, photostructuring, bonding, dicing, and coatings
- Best-in-class metrology minimizes reliability risks and enables fine resolution data across the full wafer
- Fracture mechanics glass strength experts available to train and consult on many applications

#### Multiple Compositions\* for Diverse Applications

Glass/CTE	Abbe Value v <sub>D</sub>	Refractive Index n <sub>D</sub>
SG 0.5	67.8	1.459
SG 5.1	65.0	1.487
SG 7.1	60.7	1.492
SG 7.8	61.7	1.496
SG 3.4	62.7	1.510
SG 3.6	62.7	1.510
SG 8.2	64.2	1.517
SG 9.3	58.9	1.523
SG 9.5	57.1	1.523
SG 3.8	61.9	1.523
SG 3.7	61.1	1.527
SG 9.0	55.6	1.530
SG 10.0	41.6	1.601

<sup>\*</sup>Active glasses shown here; Others available upon request

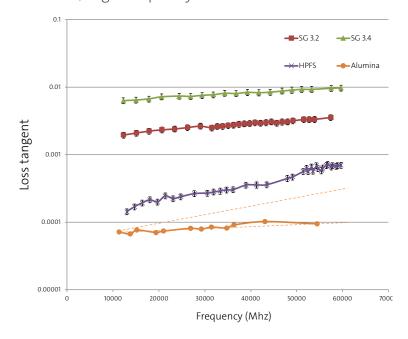
## Material Properties and Attributes

- Diameters: 100/150/200/300 mm
- Diameter tolerance\*: +/- 0.200 mm
- Thickness range: 0.10-5.0 mm
- Thickness tolerance\*: +/- 0.020 mm
- Available upon request: Various sizes/shapes/features, semi notch/flat specifications, laser serialization, laser processing, structuring, holes, bonding, coatings
- Large volume capacity: up to 60k WPM
- Typical lead-time: 2-12 weeks
- Polish scratch/dig: 20/10 to 80/50 per military spec
- World-class Tropel® FlatMaster® MSP metrology
   \*Other tighter tolerances available upon request

#### Typical Properties and Attributes

TTV	≤1 µm to ≤ 5µm
Bow	≤ 5µm to ≤ 30µm
Warp	+/- 20μm to ± 40μm
Surface roughness (Ra)	≤10Å
SORI	≤ 0.5µm to ≤ 1.5µm

## Low-loss, High-frequency Electrical Performance





Corning works closely with customers to identify the ideal set of solutions for wafer-level optics applications. We offer multiple glass and ceramic compositions, various coatings, bonding and structuring techniques, and world-class measurements to provide our customers with optimized solutions for wafer-level optic applications.

Contact us corning.com/precision-glass-solutions precisiongs@corning.com

#### Regional Sales Offices

China
Corning China (Shanghai) Regional Headquarters
6F, Li Ming Building, 111 Gui Qing Road
Shanghai, 200233, China
t: 0086 21 3338 4338
f: 0086 21 3338 4300

Europe Corning GmbH — Corning International Abraham-Lincoln-Strasse 30 65189 Wiesbaden, Germany t: +49 611 7366 159 f: +49 611 7366 143

Japan Corning International K.K Akasaka Intercity 7th floor 1-11-44 Akasaka, Minato-ku Tokyo, 107-0052, Japan t: +81 3 3586 1052 f: +81 3 3587 0906

Korea Corning Korea Company Ltd. 6th Fl., Gangnam Finance Center 152, Teheran-ro, Gangnam-gu, Seoul, 06236, Korea t: +82 2 796 9500 f: +82 2 796 9300 North America Corning Incorporated Corporate Headquarters 1 Riverfront Plaza Corning, NY 14831 United States t: 607 974 9000

Singapore
Corning Singapore Holdings Pet Ltd.
1, Kim Seng Promenade
Great World City
#9-11/12 West Tower
237994, Singapore
t: +65 65729740
f: +65 67352913

Taiwan Corning Incorporated-Taiwan 8F, No. 8, Sec.3, Minsheng E. Rd. Zhongshan Dist., Taipei City 10480 Taiwan t: +886 2 2716 0338 f: +886 2 2516 7500